

Product Change Notification / ALAN-07JWOD316

Date:

16-Nov-2022

Product Category:

Bluetooth Module

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5355 Final Notice: Qualification of MCSO as an additional fabrication site for component U4 that is one of many components within selected BM77xx and RN4677xx device families available in 33L MODULE (12x22mm) and 30L MODULE (12x15mm) packages.

Affected CPNs:

ALAN-07JWOD316_Affected_CPN_11162022.pdf ALAN-07JWOD316_Affected_CPN_11162022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of MCSO as an additional fabrication site for component U4 that is one of many components within selected BM77xx and RN4677xx device families available in 33L MODULE (12x22mm) and 30L MODULE (12x15mm) packages.

Pre and Post Change Summary:

	Pre (Change	Post Change						
Fab Site for Component U4 Within Selected Modules	Microchip Technology Tempe – Fab 2 (TMGR)	Microchip Technology Gresham – Fab 4 (GRTM)	Microchip Technology Tempe – Fab 2 (TMGR)	Microchip Technology Gresham – Fab 4 (GRTM)	Microchip Technology Colorado (MCSO)				
Wafer Diameter	8 inches	8 inches	8 inches	8 inches	6 inches				
Quality certification	ISO9001 IATF16949	ISO9001 IATF16949	ISO9001 IATF16949	ISO9001 IATF16949	ISO9001 IATF16949				
See Pre and Post change attachment.									

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying MSCO as an additional fabrication site for component U4 that is one of many components within selected BM77xx and RN4677xx device families.

Change Implementation Status: In Progress

Estimated First Ship Date: January 1, 2023 (date code: 2301)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2022					>	January 2023				
Workweek	4 5	4 6	4 7	4 8	4 9		1	3	3	4	5
Qual Report Availability			Х								
Final PCN Issue Date			Х								
Estimated Implementation Date							Х				

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: November 16, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ALAN-07JWOD316_Pre and Post Change_Summary.pdf PCN_ALAN-07JWOD316_QUAL REPORT.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

BM77SPPS5MC2-0004AA BM77SPPS3MC2-0007AA BM77SPPS3MC2-0006AA BM77SPPS3MC2-0008AA BM77SPPS3MC2-PH07AA BM77SPP03MC2-0004AA BM77SPP03MC2-0006AA BM77SPP05MC2-0006AA BM77SPP03MC2-0007AA BM77SPP03MC2-0003AA BM77SPP03MC2-0008AA BM77SPP03MC2-0009AA RN4677-V/RM112 BM77SPPS3MC2-000AAA BM77SPPS3MC2-S00AAA RN4677-V/RM100 BM77SPP03MC2-000AAA BM77SPP03MC2-000BAA